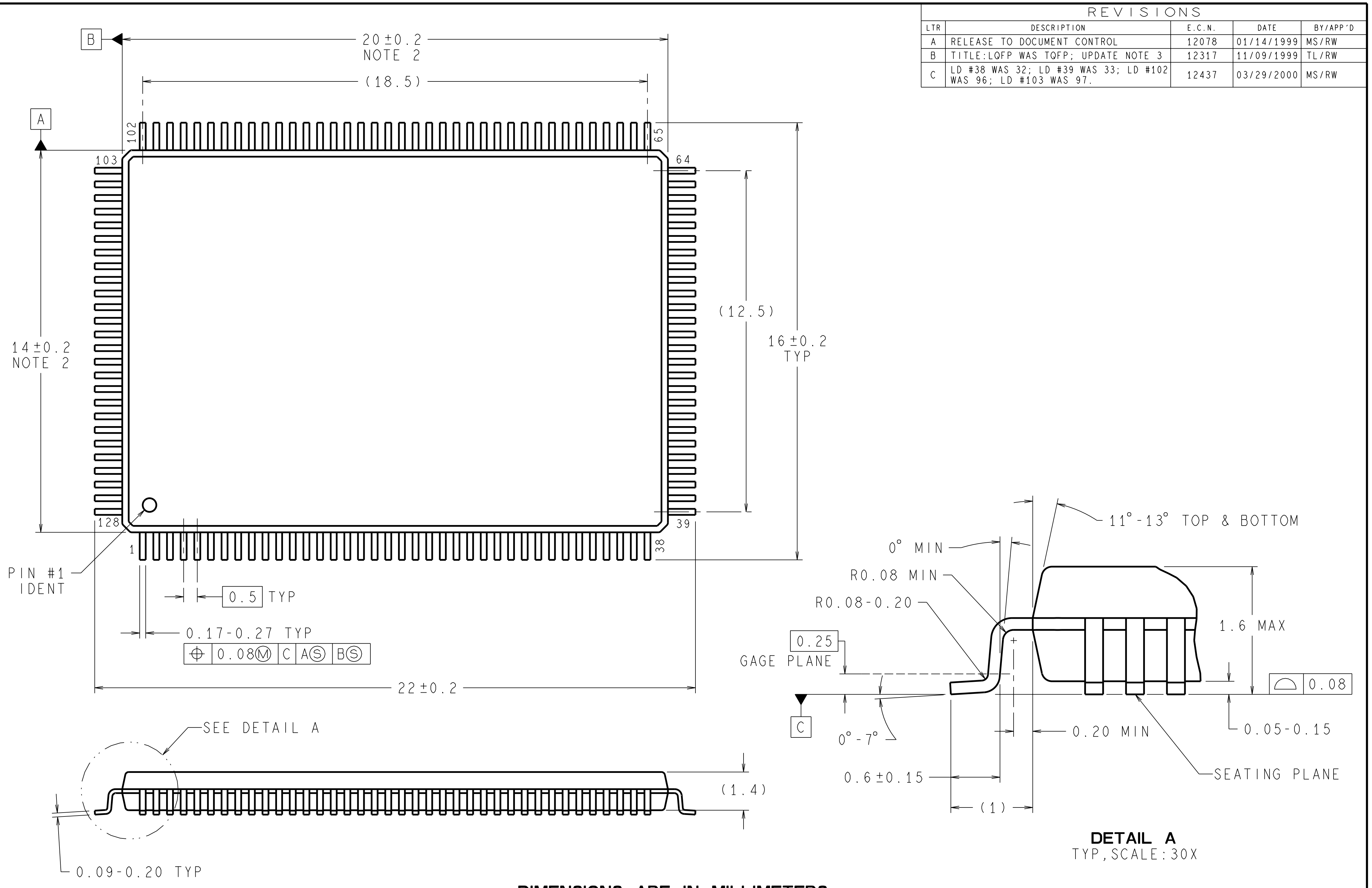
REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12078	01/14/1999	MS/RW
B	TITLE:LQFP WAS TQFP; UPDATE NOTE 3	12317	11/09/1999	TL/RW
C	LD #38 WAS 32; LD #39 WAS 33; LD #102 WAS 96; LD #103 WAS 97.	12437	03/29/2000	MS/RW



DETAIL A
TYP,SCALE:30X

DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. STANDARD LEAD FINISH:
   7.62 MICROMETERS MINIMUM SOLDER PLATING (85/15)
   THICKNESS ON COPPER.
2. DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.
   MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.
3. REFERENCE JEDEC REGISTRATION MS-026, VARIATION BHB, DATED FEBRUARY 1999.

APPROVALS	DATE
DRAWN *MARTA SUCHY*	07/10/1995
DFTG. CHK. *THANH LEQUANG*	03/31/2000
ENGR. CHK. *RANDALL WALBERG*	03/31/2000

National Semiconductor
2900 Semiconductor Dr, Santa Clara, CA 95052-8090

LQFP,
14 x 20 x 1.4mm BODY,
128 LEAD, 0.5mm PITCH

PROJECTION
INCH
[MM]

SCALE	SIZE	DRAWING NUMBER	REV
N/A	C	(SC)MKT-VLB128A	C

FORMERLY: N/A

SHEET 1 of 1